

Applications:



VR/AR



Wearable Earbuds



Smarthome



P= 0.3mm



Ultra Low Profile

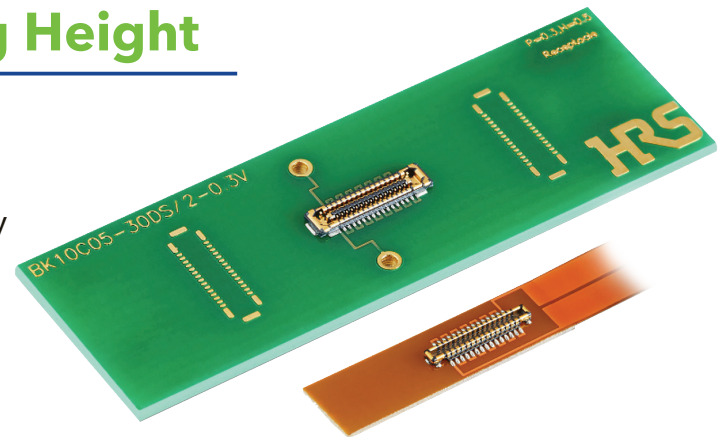


Full Armored

0.3mm Pitch, 0.5mm Stacking Height

Fully Armored, Hybrid FPC-to-Board Connector

- Ultra low-profile design with high power supply capacity
 - Stacking Height: 0.5mm, Depth: 1.7mm
 - Rated Current: Power contact 5A, Signal contact 0.3A
- Fully armored design ensures high durability
- Dimpled lock design on contacts enables high extraction force
- Easy mating operation with wide self alignment range
 - Pitch Direction: $\pm 0.29\text{mm}$
 - Width Direction: $\pm 0.24\text{mm}$
- Multi-point soldering enhances PCB peeling strength



Patented

Fully Armored Design

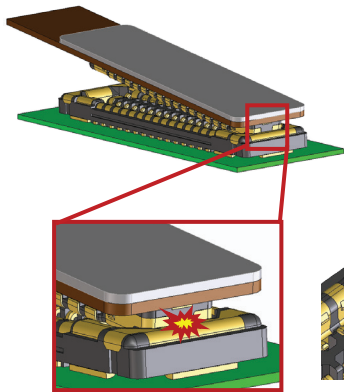
Dimple for Lock Design on the Contacts

Specifications

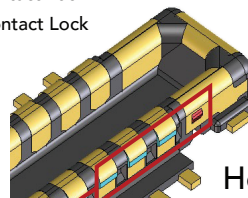
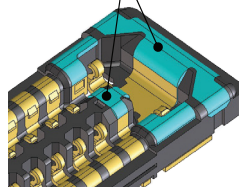
Significant Reduction in Housing Damage Due to Misalignment

Achieves High Extraction Force

- Signal Contact Lock
- Power Contact Lock

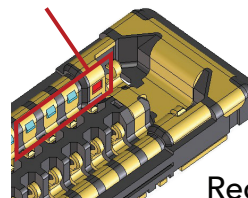


All Mating Surfaces covered in metal



Header

Contact Lock



Receptacle

Rated Current	Power Contact: 5A Signal Contact: 0.3A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +85°C*
Contact Resistance	Power Contact: 30mΩ Max. Signal Contact: 50mΩ Max.
Withstanding Voltage	100V AC for 1 min.
Insulation Resistance	50MΩ min. (100V DC)
Mating Durability	10 times

*Includes the temperature rise due to current flow.
No. of Pos.:30pos.



For additional information please go to www.hirose.com/product/series/BK10

Specifications herein are subject to change without notice.
Contact Hirose for latest specifications, drawings, or availabilities.

STAY CONNECTED

